

Brief Data Sheet

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Major Specifications

Processor Core

- ARM Cortex-A7@ 900 MHz, 32 KB I-Cache, 32 KB D-Cache/128 KB L2 cache
- NEON acceleration and the integrated floating-point processing unit (FPU)

Video Encoding

- H.264 BP/MP/HP, supporting I-/P-frames
- H.265 MP, supporting I-/P-frames
- MJPEG/JPEG baseline encoding

Video Encoding Performance

- Maximum resolution for H.264 /H.265 encoding: 2688 x 1520 or 2592 x 1944 (with the width up to 2688)
- Real-time multi-stream H.264/H.265 encoding capability:
 - 2048 x 1536@30 fps + 720 x 576@30 fps
 - 2304 x 1296@30 fps + 720 x 576@30 fps
 - 2688 x 1520@25 fps + 720 x 576@25 fps
 - 2592 x 1944@15 fps + 720 x 576@15 fps
- JPEG snapshot at 4M (2688 x 1520)@5 fps or 5M (2592 x 1944)@5 fps
- CBR, VBR, FIXQP, AVBR, QPMAP and CVBR bit rate control modes
- Intelligent encoding mode
- Up to 60 Mbit/s output bit rate
- Encoding of eight ROIs

Intelligent Video Analysis

- IVE
- Various intelligent analysis applications, such as intelligent motion detection, perimeter defense, and video diagnosis

Video and Graphics Processing

- 3DNR, image enhancement, and DCI
- Anti-flicker for output videos and graphics
- 1/15x to 16x video and graphics scaling
- Overlaying of videos and graphics
- Picture rotation by 90°, 180°, or 270°
- Picture mirror and flip
- OSD overlaying of eight regions before encoding

ISP

- 4 x 4 pattern RGB-IR sensor
- 3A (AE, AF, and AWB) function. The third-party 3A algorithms are supported.
- FPN removal and DPC
- LSC, LDC, and purple fringing correction
- Direction-adaptive demosaic
- Gamma correction, DCI, and color management and enhancement
- Adaptive region defog
- Multi-level NR (BayerNR and 3DNR) and sharpening

enhancement

- Local tone mapping
- Sensor built-in WDR
- 2F- WDR line-based mode /2F-WDR frame-based mode
- DIS
- Intelligent ISP tuning and ISP tuning tools for the PC

Audio Encoding and Decoding

- Voice encoding/decoding complying with multiple protocols by using software
- Compliance with the G.711, G.726, and ADPCM protocols
- Audio 3A functions (AEC, ANR, and AGC)

Security Engine

- AES/RSA encryption and decryption algorithms implemented by using hardware
- HASH (SHA1/SHA256/HMAC_SHA1/HMAC_SHA256) algorithms implemented by using hardware
- Integrated 32-kbit OTP storage space and random number generator

Video Interfaces

- Input
 - 8-/10-/12-bit RGB Bayer DC timing video input.
 BT.1120 input is supported.
 - MIPI, LVDS/sub-LVDS, and HiSPi
 - Compatibility with mainstream HD CMOS sensors provided by Sony, ON, OmniVision, and Panasonic
 - Compatibility with the electrical specifications of parallel and differential interfaces of various sensors
 - Programmable sensor clock output
 - Maximum input resolution: 2688 x 1520 or 2592 x 1944
- Output
 - 6-/8-/16-bit LCD output
 - BT.656/BT.1120 output

Audio Interfaces

- Integrated audio codec, supporting 16-bit audio input and output
- 2-channel MIC/line-in input
- 2-channel line-out output
- I²S interface for connecting to external audio codec

Peripheral Interfaces

- POR
- Integrated high-precision RTC
- Integrated 4-channel LSADC
- Three UART interfaces
- I²C, SPI, and GPIO interfaces
- Four PWM interfaces
- Two SDIO 2.0 interfaces
- One USB 2.0 host/device interface
- Integrated FE PHY, supporting TSO network acceleration
- PMC standby control unit



External Memory Interfaces

- SDRAM interface
 - Built-in 1 Gbit/s DDR3L SDRAM
- SPI NOR flash interface
 - 1-/2-/4-line mode
 - Maximum capacity: 256 MB
- SPI NAND flash interface
 - 1-/2-/4-line mode
 - Maximum capacity: 1 GB
- eMMC 5.0 interface - 4-/8-bit data width

Boot

- Booting from the SPI NOR flash memory, SPI NAND flash memory, or eMMC
- Secure boot

SDK

- Huawei LiteOS/Linux-4.9-based SDK
- High-performance H.264 PC decoding library
- High-performance H.265 PC, Android, and iOS decoding libraries

Physical Specifications

- Power consumption
 - Typical power consumption in the 3M30/4M15 scenario: 1 W
- Operating voltages
 - 0.9 V core voltage
 - 3.3 V I/O voltage (±10%)
 - 1.35 V DDR3L SDRAM interface voltage
- Packaging
 - 12 mm x 13.3 mm, 279 pins, 0.65 mm ball pitch, TFBGA package



Functional Block Diagram



Hi3516E V300 is a new-generation SoC designed for the industry-dedicated HD IP camera. It has an integrated new-generation ISP and the latest H.265 video compression encoder in the industry. It uses the advanced low-power technology and architecture design. All of these features enable Hi3516E V300 to lead the industry in the low bit rate, high picture quality, and low power consumption. The POR, RTC, and audio codec are integrated to greatly reduce the EBOM cost. Hi3516E V300 also provides interface designs similar to the HiSilicon DVR and NVR SoCs, facilitating rapid mass production.

Hi3516E V300 HD IP Camera Solution



Acronyms and Abbreviations

3DNR	three-dimensional noise reduction
BP	Baseline Profile
AE	automatic exposure
AES	advanced encryption standard
AF	auto focus
AWB	automatic white balance
CBR	constant bit rate
DDR	double data rate
DES	data encryption standard
DIS	digital image stabilization
EBOM	engineering bill of materials
eMMC	embedded multimedia controller
HD	high definition
HDMI	high definition multimedia interface
HiSPi	high-speed serial pixel interface
HP	High Profile
IR	infrared spectrum
ISP	image signal processor
IVE	intelligent video engine
LSADC	low-speed analog-to-digital converter
LSC	lens shading correction
LVDS	low-voltage differential signaling
MIC	microphone



MIPI	mobile industry processor interface
MP	Main Profile
NR	noise reduction
OSD	on-screen display
OTP	one-time programmable
POR	power-on reset
PWM	pulse-width modulation
QFN	Quad Flat No-lead Package
ROI	region of interest
RSA	Rivest-Shamir-Adleman
RTC	real-time clock
SDIO	secure digital input output
SDK	software development kit
SDRAM	synchronous dynamic random access memory
SoC	system on a chip
UART	universal asynchronous receiver transmitter
VBR	variable bit rate
VI	video input
VO	video output
WDR	wide dynamic range